AMENDMENTS TO THE CLAIMS

1-16. (canceled)

17. (currently amended) An intermediate structure formed during the manufacture of a printed circuit board, comprising:

a substrate comprised of a material having a first conductivity, wherein the substrate material is uncured;

at least one metal trace formed on the uncured substrate; and

a plating voltage in contact with the uncured substrate material, but not in touch with the at least one metal trace, for forming an electrolytic plating layer ~~coated~~ on at least a portion of the at least one metal trace.

18. (previously presented) The intermediate structure of claim 17, wherein the at least one metal trace is fully coated by the plating layer.

19. (previously presented) The intermediate structure of claim 17, wherein the at least one metal trace is only partially covered by the plating layer.

20. (previously presented) The intermediate structure of claim 17, wherein said first conductivity is in a range between approximately 10^6 and 10^8 ohms per square centimeter.

21. (previously presented) The intermediate structure of claim 17, wherein the substrate comprises a carbon-impregnated epoxy.

22. (previously presented) The intermediate structure of claim 17, wherein the substrate comprises a polyimide.

23. (previously presented) The intermediate structure of claim 17, wherein the substrate with the at least one metal trace and the electrolytic plating layer is subsequent curable to change its conductivity from the first conductivity to a second lower conductivity.